## Winstar Display Co., LTD 華凌光電股份有限公司



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#### **SPECIFICATION**

CUST	OME	<b>R</b> :_				
MODULE NO.:			V	<b>7</b> 0	12864H-1	`FH#
APPR	OVE	D BY:				
( FOR CUST	OMER	USE ONLY	7)		PCB VERSION:	DATA:
						_
SALES I	BY	APPROV	ED BY		CHECKED BY	PREPARED BY
VERSION	Γ	OATE	REVISE PAGE N		SUN	MMARY
0	2011	/10/14			First issue	



MODLE NO:

REC	CORDS OF RE	DOC. FIRST ISSUE	
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2011/10/14		First issue

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### 1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type O→COG Type

3 Display Font: 128 x 64 dots

Model serials no.

Special Code

 $\ \$  Backlight Type: N $\rightarrow$ Without backlight T $\rightarrow$ LED, White

 $B \rightarrow EL$ , Blue green  $A \rightarrow LED$ , Amber  $D \rightarrow EL$ , Green  $R \rightarrow LED$ , Red  $W \rightarrow EL$ , White  $O \rightarrow LED$ , Orange  $F \rightarrow CCFL$ , White  $G \rightarrow LED$ , Green  $Y \rightarrow LED$ , Yellow Green  $P \rightarrow LED$ , Blue

© LCD Mode : B→TN Positive, Gray T→FSTN Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 range/ View G→Reflective, W. T, 6:00 direction

0 C→Transmissive, N.T,6:00 00 F→Transmissive, N.T,12:00

J→Reflective, W. T, 12:00 B→Transflective, N.T,6:00

I→Transmissive, W. T, 6:00

K→Transflective, W.T,12:00

E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00 #:Fit in with the ROHS Directions and regulations

### 2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)

## 3.General Specification

Item	Dimension	Unit
Number of Characters	128 x 64 dots	_
Module dimension	80.0x 54.0 x9.5	mm
View area	70.7 x 38.8	mm
Active area	66.52 x 33.24	mm
Dot size	0.48 x0.48	mm
Dot pitch	0.52 x 0.52	mm
LCD type	FSTN Positive, Transflective (In LCD production, It will occur slightly color can only guarantee the same color in the same by	
Duty	1/65 , 1/9 Bias	
View direction	6 o'clock	
Backlight Type	LED White	

## **4.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{\mathrm{OP}}$	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	V <sub>I</sub>	-0.3	_	V <sub>DD</sub> +0.3	V

## **5.Electrical Characteristics**

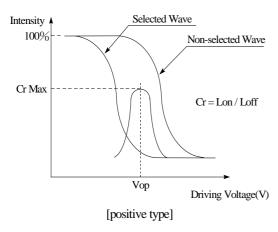
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	3.0	3.3	3.6	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	$V_{DD}$ - $V_5$	Ta=25°C	_	10.0	_	V
		Ta=70°C	_	_	_	V
Input High Volt.	$V_{\mathrm{IH}}$	_	$0.7~V_{DD}$	_	$V_{DD}$	V
Input Low Volt.	$V_{IL}$		Vss	_	$0.3  \mathrm{V}_{\mathrm{DD}}$	V
Output High Volt.	$V_{OH}$	_	$0.8 V_{DD}$	_	$V_{DD}$	V
Output Low Volt.	$V_{OL}$	_	Vss	_	$0.2V_{DD}$	V
Supply Current(No include LED Backlight)	$I_{\mathrm{DD}}$	V <sub>DD</sub> =3.3V	_	2.0	-	mA

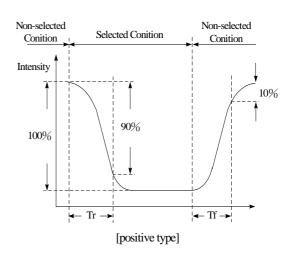
## **6.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	CR≧2	30	_	60	deg
view i migre	(H) φ	CR≧2	-45	_	45	deg
Contrast Ratio	CR	_	_	5	_	_
Response Time	T rise	_	_	350	500	ms
	T fall	_	_	150	200	ms

#### **Definition of Operation Voltage (Vop)**

#### **Definition of Response Time (Tr, Tf)**



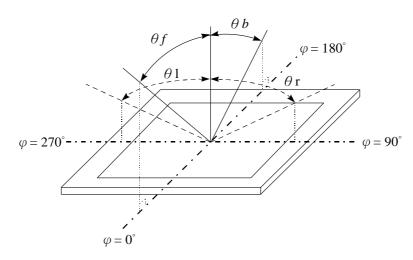


#### **Conditions:**

Operating Voltage : Vop Viewing Angle( $\theta$ ,  $\varphi$ ) :  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency : 64~HZ Driving Waveform : 1/N~duty , 1/a~bias

#### Definition of viewing angle ( $CR \ge 2$ )



## **7.Interface Pin Function**

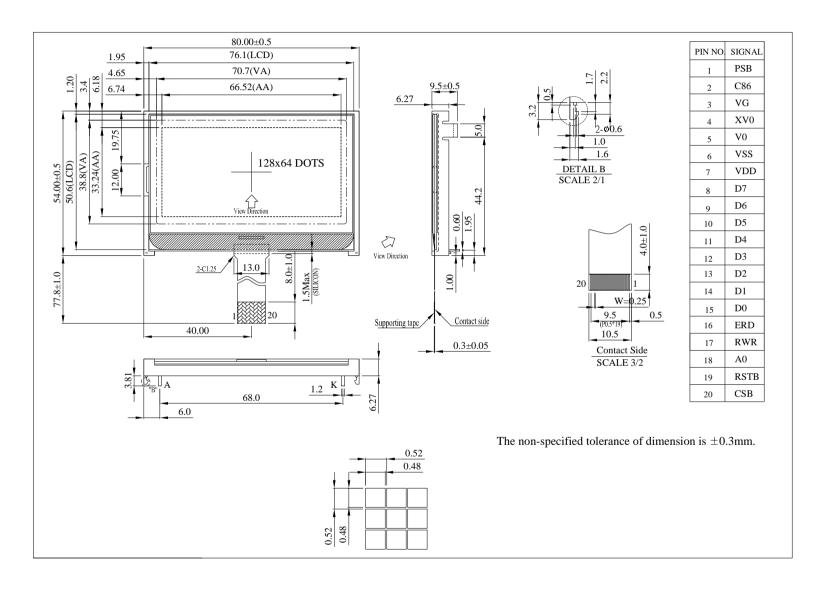
Pin No.	Symbol	Level	Description					
1	PSB	I	PSB selec	PSB selects the interface type: Serial or Parallel.				
			C86 selects the microprocessor type in parallel interface mode					
			PSB	C	86	Selected Interface		
			"H"	"H	<del>I</del> "	Parallel 6800 Series MPU Interface		
2	C86	I	"H"	"I	·	Parallel 8080 Series MPU Interface		
			"L"	"∑	Κ"	Serial 4-Line SPI Interface		
						ICATION NOTES" and		
			"Micropro					
			,			d connection of the selected interface.		
3	VG	Power	VG is the	LCD	driving	g voltage for segment circuits.		
4	XV0	Power	positive fi	rame.		ng voltage for common circuits at		
5	V0	Power	V0 is the frame.	LCD d	lriving	y voltage for common circuits at negative		
6	VSS		This is a 0V terminal connected to the system GND.					
7	VDD		Shared wi	Shared with the MPU power supply terminal VDD. (3.3 V)				
8	D7		When using 8-bit parallel interface: (6800 or 8080 mode)					
9	D6		microproc		nai dai	ta bus. Connect to the data bus of 8-bit		
10	D5		When CS	B is no	on-acti	ive (CSB="H"), D[7:0] pins are high		
11	D4		impedanc When usi		rial in	terface: 4-LINE		
12	D3		D7=SDA					
13	D2		D6=SCL D[5:0] are			d should connect to "H" by VDD1 or		
14	D1		VDDH.			ive (CSB="H"), D[7:0] pins are high		
15	D0		impedanc		on acti	(10 (CSB- 11 ), B[7.0] pins are high		
			Read/Wri	ite exec	cution	control pin. When PSB is "H",		
			C86 MPU	U Type	ERD	Description		
						Read/Write control input pin.		
			. 6	800	_	R/W="H": When E is "H", D[7:0] are in output		
16	ERD	I	H se	eries	E	mode.		
	EKD	1				R/W="L": Signals on D[7:0] are latched at the falling edge of E signal.		
			8	8080		Read enable input pin.		
			L	eries	/RD When /RD is "L", D[7:0] are in output mode.			
			ERD is no	ot used	in ser	rial interface and should fix to "H" by		
			VDD1 or					

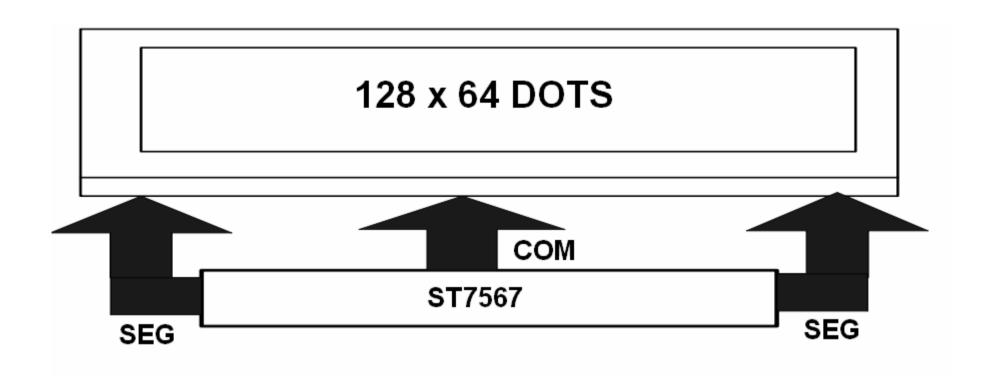
			Read	/Write exe	cution	control pin. When PSB is "H",			
			C86 MPU Type RWR Description						
				6800		Read/Write control input pin.			
			Н	series	R/W	R/W="H": read.			
17	RWR	I		301103		R/W="L": write.			
1,	10,410	•		8080		Write enable input pin.			
			L		WR	Signals on D[7:0] will be latched at the rising			
						edge of /WR signal.			
			RWF	RWR is not used in serial interface and should fix to "H" by					
			VDD1 or VDDH.						
			It determines whether the access is related to data or						
18	A0	Ţ	command.						
	710	1	A0="H": Indicates that signals on D[7:0] are display data.						
			A0="L": Indicates that signals on D[7:0] are command.						
			Hardware reset input pin. When RSTB is "L", internal						
19	RSTB	I	initialization is executed						
				and the internal registers will be initialized.					
			Chip select input pin. Interface access is enabled when CSB is						
20	CSB	I	"L".When CSB is non-active (CSB="H"), D[7:0] pins are high						
				impedance.					

### C1=C2=1UF/0805

PIN NO.	SIGNAL	
1	PSB	P3.6
2	C86	P3.6
3	VG	3 19
4	XV0	
5	V0	
6	VSS	VSS
7	VDD	VDD
8	D7	P1.7
9	D6	P1.6
10	D5	P1.5
11	D4	P1.4
12	D3	P1.3
13	D2	P1.2
14	D1	P1.1
15	D0	P1.0
16	ERD	P3.4
17	RWR	P3.7
18	A0	P3.0
19	RSTB	P3.2
20	CSB	P3.3

## **8.Contour Drawing & Block Diagram**





## 9. Timing Characteristics

Please consult the spec of ST7567

## **10.Reliability**

Content of Reliability Test (wide temperature, -20°C~70°C)

	Environmental Test						
Test Item	Content of Test	<b>Test Condition</b>	Note				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2				
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs					
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1				
High Temperature/ Humidity Operation	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2				
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles					
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5k $\Omega$ CS=100pF 1 time					

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

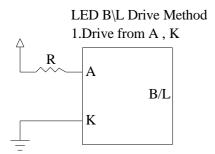
# **11.Backlight Information**

### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	86.4	96	144	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	
Reverse Voltage	VR	_	_	5	V	_
Luminous Intensity (Without LCD)	IV	672.8	755	_	CD/M <sup>2</sup>	ILED=96mA
LED Life Time (For Reference only)	_	_	50K	_	Hr.	ILED≤96mA 25°C,50-60%RH, (Note 1)
Color	White					

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



# 12. Inspection specification

NO	Item	Criterion					
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>					
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>					
03	LCD black spots, white spots, contamination (non-display)	$ \begin{array}{c c} & \Phi \leq 0.10 & Acc\\ \hline 0.10 < \Phi \leq 0.20 & \\ \hline 0.20 < \Phi \leq 0.25 & \\ \hline 0.25 < \Phi & \\ \hline \end{array} $ 3.2 Line type : (As following drawing)	eptable Q TY ept no dense 2 1 0  ptable Q TY				
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	ept no dense  2 round type				
04	Polarizer bubbles	judge using black spot	ept no dense  3 2 0 3				

NO	Item		Criterion		AQL	
05	Scratches	Follow NO.3 LCD blac	ek spots, white spots, con	ntamination		
		<ul><li>k: Seal width t:</li><li>L: Electrode pad length</li><li>6.1 General glass chip :</li></ul>	Glass thickness a: LC	ip thickness D side length panels:		
		z: Chip thickness	y: Chip width	x: Chip length		
	Chipped	Z≦1/2t	Not over viewing area	x ≤ 1/8a		
06	glass	$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a	2.5	
		<ul><li>⊙ If there are 2 or more chips, x is total length of each chip.</li><li>6.1.2 Corner crack:</li></ul>				
		z: Chip thickness	y: Chip width	x: Chip length		
		Z≦1/2t	Not over viewing area	x ≤ 1/8a		
		$1/2t < z \le 2t$	Not exceed 1/3k	x≤1/8a		
		⊙ If there are 2 or more	chips, x is the total lengtl	n of each chip.		

NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
		$\begin{array}{ c c c c c c }\hline y: Chip \ width & x: Chip \ length & z: Chip \ thickness \\\hline y \le 0.5 mm & x \le 1/8a & 0 < z \le t \\\hline 6.2.2 \ Non-conductive portion: \\\hline \end{array}$	
06	Glass crack	y Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$	
		<ul> <li>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</li> <li>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</li> <li>6.2.3 Substrate protuberance and internal crack.</li> </ul>	
		y: width x: length	
		$y \le 1/3L$ $x \le a$	
		У	

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
10	PCB · COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5 2.5
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> </ul>	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

# 13. Material List of Components for

## **RoHs**

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

.

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limit	ed value is s	et up accordi	ing to RoHS	•		

- 2. Process for RoHS requirement:
- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow:  $250^{\circ}$ C, 30 seconds Max.;

Connector soldering wave or hand soldering :  $320^{\circ}$ C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.  $: 235\pm5^{\circ}\mathbb{C}$  ;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

## 14. Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module

<b>a</b> Lodule	winstar LCM Samp e Number :		e Feedback Sheet Page: 1
	anel Specification:		<del></del>
	Panel Type:	Pass	□ NG ,
2.	View Direction:	☐ Pass	□ NG ,
3.	Numbers of Dots:	Pass	☐ NG ,
4.	View Area:	☐ Pass	☐ NG ,
5.	Active Area:	☐ Pass	☐ NG ,
6.	Operating Temperature:	Pass	☐ NG ,
7.	Storage Temperature:	Pass	☐ NG ,
8.	Others:		
2 · <u>M</u>	Iechanical Specification		
1.	PCB Size:	Pass	□ NG ,
2.	Frame Size:	☐ Pass	□ NG ,
3.	Materal of Frame:	☐ Pass	□ NG ,
4.	Connector Position:	Pass	☐ NG ,
5.	Fix Hole Position: A	Pass	☐ NG ,
6.	Backlight Position:	☐ Pass	☐ NG ,
7.	Thickness of PCB:	Pass	□ NG ,
8.	Height of Frame to PCB:	☐ Pass	☐ NG ,
9.	Height of Module:	Pass	□ NG ,
10.	Others:	Pass	□ NG ,
3 \ <u>R</u>	telative Hole Size:		
1.	Pitch of Connector:	Pass	□ NG ,
2.	Hole size of Connector:	Pass	□ NG ,
3.	Mounting Hole size:	Pass	□ NG ,
4.	Mounting Hole Type:	Pass	□ NG ,
5.	Others:	Pass	□ NG ,
4 \ <u>B</u>	acklight Specification:		
1.	B/L Type:	Pass	□ NG ,
2.	B/L Color:	Pass	□ NG ,
3.	B/L Driving Voltage (Refere	nce for LED	Type):   Pass   NG,
4.	B/L Driving Current:	☐ Pass	□ NG ,
5.	Brightness of B/L:	☐ Pass	□ NG ,
6.	B/L Solder Method:	Pass	□ NG ,
7.	Others:	Pass	□ NG ,

Number:		Page: 2
Electronic Characteristics of	f Module :	
Input Voltage:	Pass	☐ NG ,
Supply Current:	Pass	□ NG ,
Driving Voltage for LCD:	Pass	□ NG ,
Contrast for LCD:	Pass	☐ NG ,
B/L Driving Method:	Pass	☐ NG ,
Negative Voltage Output:	Pass	☐ NG ,
Interface Function:	Pass	□ NG ,
LCD Uniformity:	Pass	□ NG ,
ESD test:	Pass	☐ NG ,
Others:	Pass	☐ NG ,
Sales signature : Customer Signature :		